

BONDING METHOD AND APPARATUS

ABSTRACT OF THE DISCLOSURE

5 A bonding method and apparatus for performing same in which a first member (e.g., a silicon chip) is bonded to a second member (e.g., a glass substrate such as a PCB) using a thermosetting resin adhesive. Near infrared rays are directed onto the second member, some of these passing through the second member to also heat the adhesive. A heater is pressed onto the first member and also heats the first member. Selective cooling is also utilized to assure an acceptable temperature gradient between both members and thereby prevent distortion of same which could harm the resulting structure.